



12/30/03

01-06-2004



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

REQUEST FOR ASSIGNMENT RECORDAL

Mail Stop Assignment Recordation Services
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Please record the attached assignment document.

1. Names of conveying parties: Masazumi AMAGAI
Masako WATANABE
Kensho MURATA
Osamu MUNAKATA
Yoshitaka TOYODA
Minoru UESHIMA
Tsukasa OHNISHI
Hiroshi OKADA
2. Name and address of receiving parties: SENJU METAL INDUSTRY CO., LTD.
23 Senju-Hashido-cho
Adachi-ku, Tokyo 120-8555
Japan
3. Nature of conveyance: Assignment
Execution Dates: December 15, 2003 for AMAGAI
December 11, 2003 for WATANABE
December 11, 2003 for MURATA
November 28, 2003 for MUNAKATA
November 28, 2003 for TOYODA
November 28, 2003 for UESHIMA
November 28, 2003 for OHNISHI
December 3, 2003 for OKADA
4. Application No.: 10/614,351
Filing date: July 8, 2003

01/05/2004 DEYNE 00000073 10614351 40.00 DP
01 FC:8021

5. Name and address of party to whom correspondence concerning the attached document should be mailed:

Michael Tobias
#40
1717 K Street N.W., Suite 613
Washington, D.C. 20036

6. Total number of patent applications involved: 1

7. Total fee: \$40.00
[X] Enclosed
[] Authorized to be charged to the deposit account
[X] The Commissioner is authorized to charge any deficiencies in the fee payment accompanying this communication and to credit any excess payment of fees to Deposit Account No. 50-1079.

8. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Dec 30, 2003
Date

Michael Tobias
Michael Tobias
Registration No. 32,948

Total number of pages comprising cover sheet, attachments and document: 4

ASSIGNMENT

WHEREAS, We, Masazumi AMAGAI, Masako WATANABE, Kensho MURATA, Osamu MUNEKATA, Yoshitaka TOYODA, Minoru UESHIMA, Tsukasa OHNISHI, and Hiroshi OKADA, residing in Tsukuba-shi, Ibaraki; Oita-shi, Oita; Beppu-shi, Oita; Souka-shi, Saitama; Satte-shi, Saitama; Misato-shi, Saitama; Souka-shi, Saitama; and Souka-shi, Saitama, respectively, have invented certain new and useful improvements entitled

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(a) for which an application for United States Letters Patent was filed on
July 8, 2003
and identified by United States Serial No. 10/614,351; or

(b) for which an application for United States Letters Patent was executed on
_____.

AND, WHEREAS, SENJU METAL INDUSTRY CO., LTD., a corporation of Japan, having a place of business at 23 Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, Japan, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to us by said assignee, the receipt of which is hereby acknowledged, we do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by us had this assignment not been made.

The Commissioner for Patents is requested to issue such Letters Patent in accordance herewith. We covenant that we are the lawful owners of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that we have the full right to make this assignment.

And for the consideration aforesaid, we agree jointly and individually that we will communicate to said assignee or the representatives thereof any facts known to us respecting said inventions and improvements, and will, upon request, but without

expense to us, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuations-in-part, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts, deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon our heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

We authorize the assignee and its agents to insert or to have inserted in this instrument the execution date/or the filing date and serial number of our patent application.

Dated: 15 Dec. 2003

Masazumi Amagai

Masazumi AMAGAI

Dated: 11 Dec. 2003

Masako Watanabe

Masako WATANABE

Dated: 11 DEC 2003

Kensho Murata

Kensho MURATA

Dated: 28 NOV 2003

Osamu Munekata

Osamu MUNEKATA

Dated: 28 Nov. 2003

Yoshitaka Toyoda

Yoshitaka TOYODA

Dated: 28 Nov. 2003

Minoru Ueshima

Minoru UESHIMA

Dated: 28 Nov. 2003

Tsukasa Ohnishi

Tsukasa OHNISHI

Dated: 3 December 2003

Hiroshi Okada

Hiroshi OKADA